Connector for SIM Card 8pins

SCGC Series



Small size surface mounting contributes to improved flexibility in set design.





Features

• Thin type 1.55mm push-push type.

Typical Specifications

• Equipped with card detection switch.

- Applications
- PCs and personal digital assistants

For W-SIM For Memory Stick Micro™

For SD Memory

Card For

microSD™ Card

For SIM Card 8pins

For Memory Stick™

Combine Type

For Compact Flash™

ltems Specifications **Applicable media** SIM Card 8pins Mounting type Surface mounting type Structure Mounting style Standard mount Media ejection Push-push type structure Operating -25℃ to +70℃ temperature range 500V AC 1minute Voltage proof Insulation $1,000 M\,\Omega$ min. resistance (Initial) Performance Connector $100m\,\Omega\,$ max. Contact contacts resistance Detection (Initial) $500m\Omega$ max. switch Insertion and 5,000cycles removal cycle

Camera Module

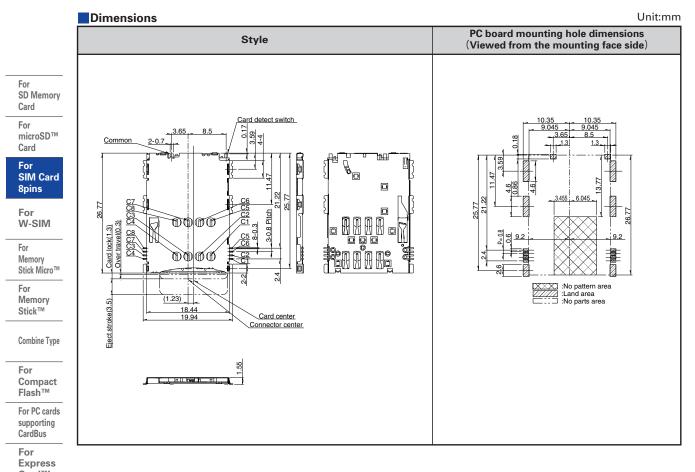
For PC cards

supporting CardBus

Product Line

Media ejection structure	Mounting style	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	0	Taping	SCGC1B0101





Card™ For CMOS Camera Module



Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 $\phi~$ CA (K) or CC (T) .
- 3. Temperature profile (Surface of products).

SD Memory Card For microSD™ Card

For

For SIM Card 8pins For

W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type



 O
 200

 Boom
 100

 Heating time
 sec.

240°C (max.)

For PC cards supporting

CardBus For Express Card™

For CMOS Camera Module

Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

